



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6R*0464AS6	A	BO2A	2016-03-30
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	5x 4.4 x0.9	14	gull wing	
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65; MDF valid for TS974IYPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KD6R*0464A56									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.345	mg	supplier	die	Silicon (Si)	7440-21-3		1.334	mg	991822	24334				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3717	91				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2230	55				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	2230	55				
Leadframe	Copper & its alloys	27.783	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.327	mg	947594	480244				
				supplier	alloy	Nickel (Ni)	7440-02-0		0.821	mg	29550	14976				
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.041	mg	1476	748				
				supplier	alloy	Silicon (Si)	7440-21-3		0.178	mg	6407	3247				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.285	mg	10258	5199				
				supplier	metallization	Palladium (Pd)	7440-05-3		0.018	mg	648	328				
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	288	146				
				supplier	metallization	Silver (Ag)	7440-22-4		0.105	mg	3779	1915				
				Die attach	Other Organic Materials	0.518	mg	supplier	glue	Silver (Ag)	7440-22-4		0.456	mg	880309	8318
				supplier				glue	Isobornyl Methacrylate	7534-94-3		0.026	mg	50193	474	
supplier	glue	Urethane Methacrylate Resin	5888-33-5					0.026	mg	50193	474					
supplier	glue	Acrylate polymer	87320-05-6					0.010	mg	19305	182					
Bonding wires	Other inorganic materials	0.076	mg	supplier	wire	Copper (Cu)	7440-50-8		0.076	mg	1000000	1386				
Encapsulation	Other Organic Materials	25.098	mg	supplier	mold compound	Silica, vitreous	60676-86-0		22.011	mg	877002	401514				
				supplier	mold compound	Epoxy resin	85954-11-6		1.004	mg	40003	18314				
				supplier	mold compound	Epoxy	29690-82-2		1.004	mg	40003	18314				
				supplier	mold compound	phenol resin	Proprietary		0.753	mg	30002	13736				
				supplier	mold compound	additive	Proprietary		0.251	mg	10001	4579				
				supplier	mold compound	carbon black	1333-86-4		0.075	mg	2988	1368				